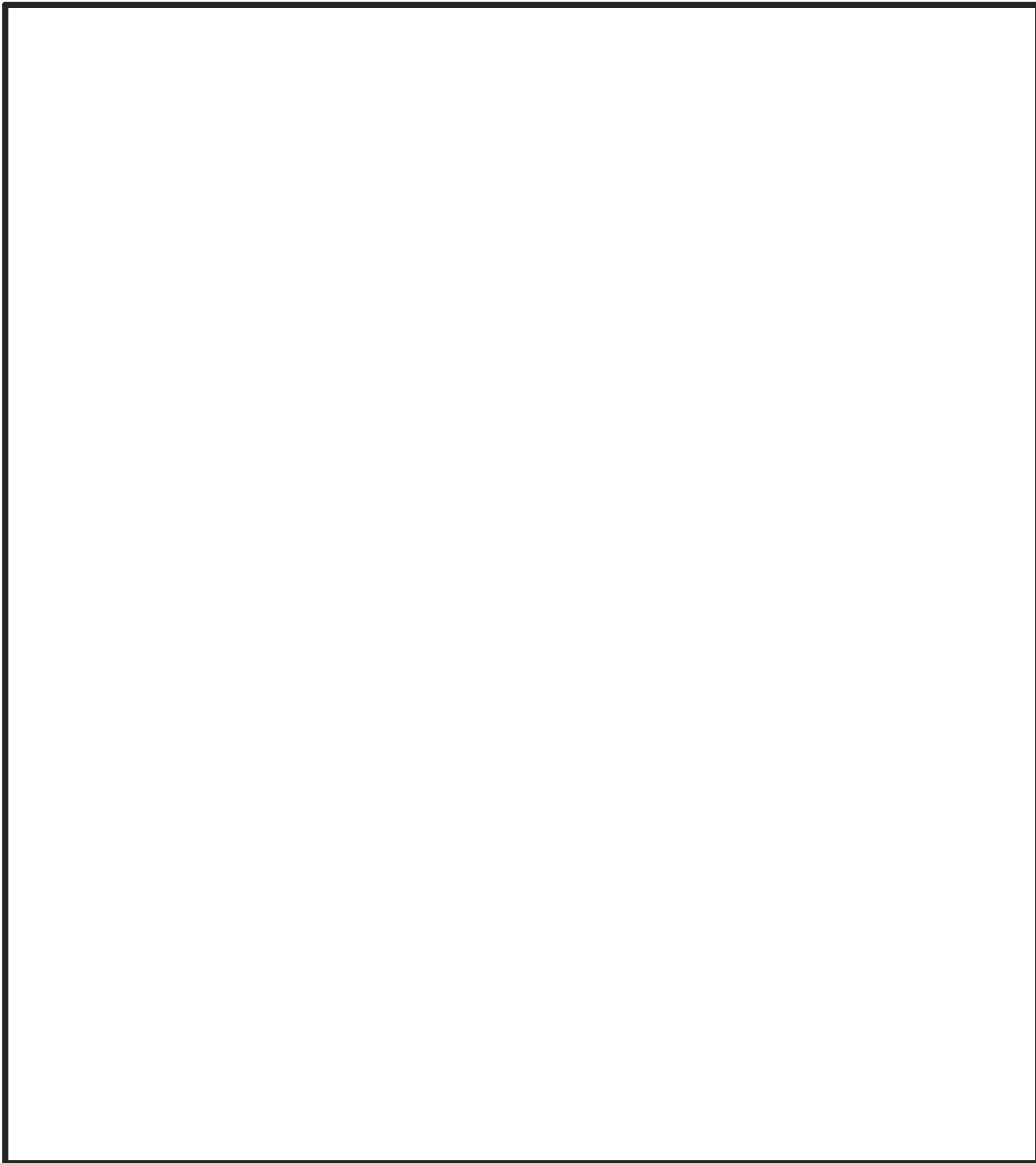


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: 001

PCB VIEWED FROM TOP SIDE	BOARD #: PMP30227	REV: A	SVN REV: Not In VersionControl
	TID #: ChangeMe!		
PLOT NAME = Top Assembly Drawing	GENERATED : 7/18/2017	10:44:36 AM	TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP30227	REV: A	SVN REV: Not In VersionControl
	TID #: ChangeMe!		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 7/18/2017 10:44:37 AM	TEXAS INSTRUMENTS	

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